



RE933-04

- Epoxy fibre-glass FR4 1.50 mm
- Double-sided 35 µm Cu
- Plated through holes (PTH)
- Surface chem. Ni/Au with solder stop mask
- Adaption circuit board for TSSOP 20
- Pitch: 0.65 mm (173 mil)
- Hole diameter 1.00 mm
- Size 15.88 x 23.50 mm

Module-No.	Pitch	mil	Pin	Size (mm)
RE933-04		0.650 mm	22.5	20 4.400 (173 mil)